Filename: PMP10416RevA_Bom.xls

UCC28700 200VAC-400VAC 50W Flyback

| Filename: PMPTU416ReVA_Bom.xl | Variant: 001 | Generated: 9/30/2014 11:02:06 AM | SVN path: SVN rev: \$Rev:: \$

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer	Alternate PartNumber	Alternate Manufacturer
!PCB1	1	7 4.40	Printed Circuit Board	- uonagonorono	PMP10416	Any	, atomato i artitambo	/ Itomato mararatara
C1	1	2200pF	CAP, CERM, 2200 pF, 250 V, +/- 20%, E, Cap, 7x12x9	Cap. 7x12x9 mm		MuRata		
	·		mm	омр, <u></u>				
C2	1	100pF	CAP, CERM, 100pF, 100V, +/-5%, C0G/NP0, 0603	0603	C1608C0G2A101J	TDK	İ	
C3, C8	2	33uF	CAP ALUM 33UF 400V 20% RADIAL	18x20mm	EEU-EB2G330S	Panasonic		
C4, C5, C6	3	330uF	CAP ALUM 330UF 35V 20% RADIAL	CAPPR5-10x16	UVR1V331MPD1TD	Nichicon		
C7	1	0.1uF	CAP, CERM, 0.1 µF, 50 V, +/- 5%, X7R, 0805	0805	08055C104JAT2A	AVX		
C9	1	10pF	CAP, CERM, 10 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603	06035A100JAT2A	AVX		
C11	1	4.7uF	CAP, CERM, 4.7 μF, 50 V, +/- 10%, X7R, 1210	1210	GRM32ER71H475KA88 L	MuRata		
C12	1	0.1uF	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	0603	06035C104KAT2A	AVX		
D1	1	150V	Diode, Schottky, 150V, 6A, DPAK	DPAK	DSS6-015AS	IXYS		
D2, D101	2	160V	Diode, TVS, Uni, 160 V, 600 W, SMB	SMB	SMBJ160A-13-F	Diodes Inc.	İ	
D3	1	1000V	DIODE GPP 1PH 4A 1000V GPP GBU	GBU	GBU4M-E3/51	Vishay-Semiconductor		
D4	1	1.7V	Diode, Ultrafast, 1000V, 1A, SMA	SMA	US1M-13-F	Diodes Inc.	İ	
D5	1	200V	Diode, Switching, 200V, 0,2A, SOD-123	SOD-123	BAV21W-7-F	Diodes Inc.		
D6	1	30V	Diode, Schottky, 30V, 0.2A, SOD-323	SOD-323	BAT54HT1G	ON Semiconductor	İ	
F1	1		FUSE FAST 250VAC 2A RADIAL	TR5 fuse 8.5mm DIA	37012000410	Littelfuse		
HS1	1		Heat Sink, TO-220, TH	TO-220 Heat Sink	530614B00000G	Aavid	İ	
J1	1	2x1	Conn Term Block, 2POS, 5.08mm, TH	PhoenixContact_1715 721	1715721	Phoenix Contact		
J2	1		HEADER, .312 VERT 3POS	19.7x10.7 x8.5 mm	1-1318301-3	TE Connectivity	İ	
L1	1	1uH	Inductor, Unshielded Drum Core, Ferrite, 1uH, 8A, 0.006 ohm. TH	D6 x 8.5mm	7447462010	Wurth Elektronik eiSos		
L2	1	10mH	Coupled inductor, 10mH, 1A, TH	17.5x22x13 mm	744822110	Wurth Elektronik eiSos		
Q1	1	1200V	MOSFET N-CH 1200V 10A TO-247	TO-247	SCT2450KEC	Rohm		None
R1, R3, R7, R9	4	511k	RES, 511 k, 1%, 0.25 W, 1206	1206	CRCW1206511KFKEA	Vishay-Dale		
R4, R5	2	10.0k	RES. 10.0 k. 1%, 0.25 W. 1206	1206	CRCW120610K0FKEA	Vishay-Dale		
R6, R8,	3	1.5Meg	RES, 1.5 M, 5%, 0.25 W, 1206	1206	CRCW12061M50JNEA	Vishay-Dale		
R10	1	200	RES, 200, 5%, 0.25 W, 1206	1206	CRCW1206200RJNEA	Vishay-Dale		
R12	1	100	RES, 100, 5%, 0.25 W, 1206	1206	CRCW1206100RJNEA	Vishav-Dale		
R13	1	105k	RES, 105 k, 1%, 0.1 W, 0603	0603	CRCW0603105KFKEA	Vishav-Dale		
R14	1	10	RES, 10 ohm, 5%, 0.1W, 0603	0603	CRCW060310R0JNEA	Vishay-Dale	İ	
R15	1	100k	RES, 100k ohm, 5%, 0.125W, 0805	0805	CRCW0805100KJNEA	Vishay-Dale		
R16	1	0	RES, 0, 5%, 0.1 W, 0603	0603	CRCW06030000Z0EA	Vishay-Dale		
R17	1	511	RES, 511, 1%, 0.1 W, 0603	0603	CRCW0603511RFKEA	Vishay-Dale		
R18	1	20.5k	RES, 20.5 k, 1%, 0.1 W, 0603	0603	CRCW060320K5FKEA	Vishay-Dale		_
R19	1	1.2	RES, 1.2, 5%, 0.75 W, 2010	2010	CRCW20101R20JNEF	Vishay-Dale		
R20	1	1.00	RES, 1.00, 1%, 0.75 W, 2010	2010		Vishay-Dale		
RT1	1	10 ohm	Thermistor NTC, 10 ohm, 20%, Disc_11.5mmx6mm	Disc_11.5mmx6mm	B57236S0100M000	EPCOS Inc		
T1	1	1 mH	Transformer, 1 mH, TH	TH, 14-Leads, Body 32.38x27.18mm, Pitch 3.81mm	750315046	Wurth Elektronik eiSos		
U1	1		Primary-Side Regulation, DBV0006A	DBV0006A	UCC28700DBV	Texas Instruments		None
C10	0	10pF	CAP, CERM, 10 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603	06035A100JAT2A	AVX		
R2	0	DNP	RES, 0 ohm, 5%, 0.125W, 0805	0805	CRCW08050000Z0EA	Vishay-Dale		

Notes:

Unless otherwise noted in the Alternate PartNumber and/or Alternate Manufacturer columns, all parts may be substituted with equivalents.

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